## PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company  STMicroelectronics International N.V		STMicroelectronics International N.V
1.2 PCN No.		ADG/19/11667
1.3 Title of PCN		TO-3P new molding compound - SP Semiconductor (Korea)
1.4 Product Category		IGBTs / Power BIPOLAR
1.5 Issue date		2019-07-11

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	FRANCKE CHRISTIANE	
2.1.2 Phone	+49 89460062128	
2.1.3 Email	christiane.francke@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Angelo RAO	
2.1.2 Marketing Manager	Natale Sandro D'ANGELO	
2.1.3 Quality Manager	Vincenzo MILITANO	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	SP Semiconductor (Korea)

4. Description of change		
	Old	New
4.1 Description	TO-3P of Subcontractor SP Semiconductor (Korea) are manufactured with SI-7200DX2 molding compound.	TO-3P of Subcontractor SP Semiconductor (Korea) will be manufactured with KTMC-1050GR molding compound.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change		
5.1 Motivation Samsung SDI production discontinuation		
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change	
6.1 Description	by FG code and Q.A. number

7. Timing / schedule	
7.1 Date of qualification results	2019-07-05
7.2 Intended start of delivery	2019-10-05
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	11667 Rel15-2019.pdf		
8.2 Qualification report and qualification results		Issue Date	2019-07-11

## 9. Attachments (additional documentations)

11667 Public product.pdf 11667 TO-3P New Molding compound - SP Semi (Korea).pdf 11667 Rel15-2019.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
2797965	STGWT15H60F	
2729673	STGWT20HP65FB	

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